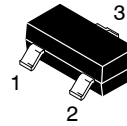


N-Channel JFET Low-Frequency Low-Noise Amplifier



- 1. Drain
- 2. Source
- 3. Gate

BSR58

SOT-23
CASE 318-08

Description

This device is designed for low-power chopper or switching application sourced from process 51.

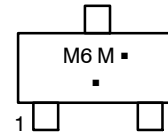
ABSOLUTE MAXIMUM RATINGS

(T_C = 25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DGO}	Drain-Source Voltage	40	V
V _{GSO}	Gate-Source Voltage	-40	V
I _{GF}	Forward Gate Current	50	mA
P _{tot}	Total Power Dissipation Up to T _{amb} = 40°C	250	mW
T _{STG}	Storage Temperature Range	-55 to +150	°C
T _J	Junction Temperature	150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MARKING DIAGRAM



- M6 = Specific Device Code
- M = Date Code
- = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BSR58	SOT-23 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

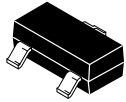
ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
BV _{GSS}	Gate-Source Voltage	V _{DS} = 0 V, I _C = 1.0 μA	40.0	-	-	V
I _{GSS}	Gate Reverse Current	V _{GS} = 20 V	-	-	1.0	nA
I _{DSS}	Zero-Gate Voltage Drain Current	V _{DS} = 15 V, V _{GS} = 0 V	8.0	-	80.0	mA
V _{GS(off)}	Gate-Source Cut-off Voltage	V _{DS} = 15 V, I _D = 0.5 nA	0.8	-	4.0	V
V _{DS(on)}	Drain-Source On Voltage	V _{GS} = 0 V, I _D = 5 mA	-	-	0.4	V
r _{ds(on)}	Drain-Source On Reverse	V _{GS} = 0 V, I _D = 0 mA	-	-	60.0	Ω
C _{rss}	Reverse Transfer Capacitance	V _{DS} = 0 V, V _{GS} = 10 V	-	-	5.0	pF
t _d	Delay Time	V _{DD} = 10 V, V _{GS(on)} = 0 V I _D = 10 mA, V _{GS(off)} = 10.0 V	-	-	10.0	ns
t _r	Rise Time		-	-	10.0	
t _{off}	Turn-off Time		-	-	100.0	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

MECHANICAL CASE OUTLINE

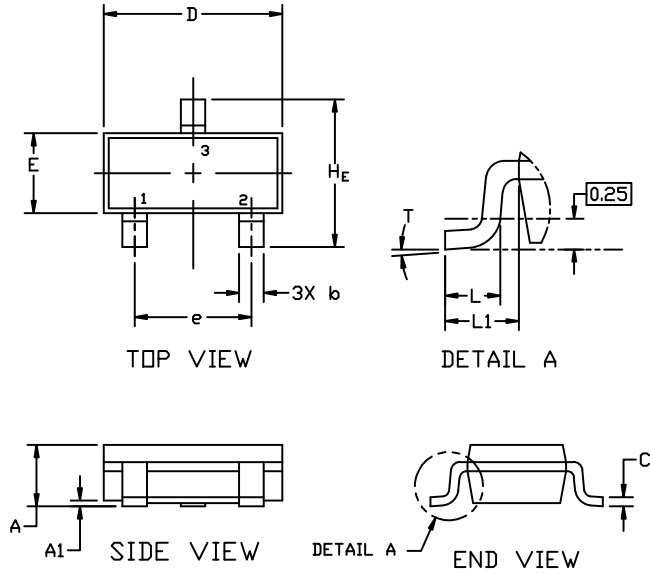
PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1

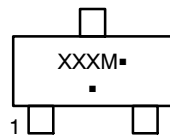


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

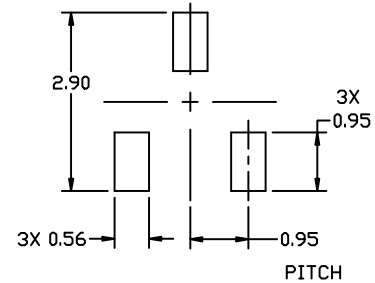
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H _E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5:
 CANCELLED

STYLE 6:
 PIN 1. BASE
 2. EMITTER
 3. COLLECTOR

STYLE 7:
 PIN 1. EMITTER
 2. BASE
 3. COLLECTOR

STYLE 8:
 PIN 1. ANODE
 2. NO CONNECTION
 3. CATHODE

STYLE 9:
 PIN 1. ANODE
 2. ANODE
 3. CATHODE

STYLE 10:
 PIN 1. DRAIN
 2. SOURCE
 3. GATE

STYLE 11:
 PIN 1. ANODE
 2. CATHODE
 3. CATHODE-ANODE

STYLE 12:
 PIN 1. CATHODE
 2. CATHODE
 3. ANODE

STYLE 13:
 PIN 1. SOURCE
 2. DRAIN
 3. GATE

STYLE 14:
 PIN 1. CATHODE
 2. GATE
 3. ANODE

STYLE 15:
 PIN 1. GATE
 2. CATHODE
 3. ANODE

STYLE 16:
 PIN 1. ANODE
 2. CATHODE
 3. CATHODE

STYLE 17:
 PIN 1. NO CONNECTION
 2. ANODE
 3. CATHODE

STYLE 18:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. ANODE

STYLE 19:
 PIN 1. CATHODE
 2. ANODE
 3. CATHODE-ANODE

STYLE 20:
 PIN 1. CATHODE
 2. ANODE
 3. GATE

STYLE 21:
 PIN 1. GATE
 2. SOURCE
 3. DRAIN

STYLE 22:
 PIN 1. RETURN
 2. OUTPUT
 3. INPUT

STYLE 23:
 PIN 1. ANODE
 2. ANODE
 3. CATHODE

STYLE 24:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE

STYLE 25:
 PIN 1. ANODE
 2. CATHODE
 3. GATE

STYLE 26:
 PIN 1. CATHODE
 2. ANODE
 3. NO CONNECTION

STYLE 27:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE

STYLE 28:
 PIN 1. ANODE
 2. ANODE
 3. ANODE

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